

**FLEXIBLE,
Solvented**

cenvar B88, B80, F81, F89, F87 & H88

flexible solvented impregnating varnishes, available in Class B, F & H

cenvar Insulating Varnishes & Impregnating Resins

Technical Data Sheet

General Characteristics

cenvar B88, B80, F81, F89, F87 & H88 are solvented impregnating varnishes, based on polyester & polyurethane / epoxy polymers. These varnishes are specially formulated to form very flexible films on curing. They are ideal for lamination / impregnation of fibre glass sleeves, tapes, films, cloths, etc. and on surfaces requiring high flexibility. These flexible varnishes are used as binder varnish for glass fibre fabric mica composite insulation in the form of sheets / tapes, etc.

These products are available in Thermal Class B (130⁰C), F (155⁰C) and H (180⁰C).

All products form clear flexible film on curing. They fast cure and can be used on regular as well as online ovens having dip or roller impregnating systems. They have good dielectric strength and good resistance to moisture, solvents, chemicals, etc. These products have a storage life of 6 months.

Flexible Varnishes :

B88	Class B - Air Dry
B80	Class B - Baking
F81	Class F - Baking
F89	Class F - Baking
F87	Class F - Baking
H88	Class H - Baking

B88

- ◆ Alkyd Polyester
- ◆ **Air Drying**, Solvented
- ◆ Thermal Class B, 130 °C
- ◆ Good Electrical properties
- ◆ Good Flexibility
- ◆ Low Cost, Clear Film
- ◆ Cures at Room Temperature
- ◆ Low Viscosity
- ◆ Solids : 34 ~ 40 %
- ◆ Dielectric Strength : >50
- ◆ Thinner T88

B80

- ◆ Polyester
- ◆ Solvented, Mild Solvents, Low Odour
- ◆ Thermal Class B, 130 °C
- ◆ Good Adhesion
- ◆ Good Flexibility
- ◆ Low Cost, Clear Film
- ◆ Low Oven Temperature (120°C~ 140°C)
- ◆ Low Viscosity
- ◆ Solids : 40 ~ 44 %
- ◆ Dielectric Strength : >50
- ◆ Thinner T80

Chetak Manufacturing Co.

cenvar

508, Bharat Chambers, Baroda Street, Mumbai 400 009 INDIA.
T: 022-66311995 E: info@cenvar.com W: www.cenvar.com

F81

- ◆ Polyester
- ◆ Solvented
- ◆ Thermal Class F, 155 °C
- ◆ Good Adhesion
- ◆ Good Flexibility
- ◆ **Fast Curing**, Clear Film
- ◆ Low Oven Temperature (120°C~160°C)
- ◆ Medium Viscosity
- ◆ Solids : 44 ~ 48 %
- ◆ Dielectric Strength : >60
- ◆ Thinner T80

F89

- ◆ **Polyurethane**
- ◆ Solvented
- ◆ Thermal Class F, 155 °C
- ◆ Good Adhesion
- ◆ **Excellent Flexibility**
- ◆ High Film Built-up, Clear Film
- ◆ Low Oven Temperature (150°C~200°C)
- ◆ Low Viscosity
- ◆ Solids : 48 ~ 52 %
- ◆ Dielectric Strength : >60
- ◆ Thinner T80

F87

- ◆ **Epoxy Modified**
- ◆ Thermal Class F, 155 °C
- ◆ Fast Curing
- ◆ High Penetration
- ◆ **High Bond Strength & Adhesion**
- ◆ Good Flexibility
- ◆ Low Oven Temperature (200°C~300°C)
- ◆ Low Viscosity
- ◆ High Solids : 44 ~ 48 %
- ◆ Dielectric Strength : >60
- ◆ Thinner T87

H88

- ◆ Polyesterimide Modified
- ◆ **Thermal Class H, 180 °C**
- ◆ Fast Curing
- ◆ High Penetration
- ◆ **High Bond Strength & Adhesion**
- ◆ Good Flexibility
- ◆ Medium Oven Temp. (250°C~350°C)
- ◆ Low Viscosity
- ◆ High Solids : 44 ~ 48 %
- ◆ Dielectric Strength : >60
- ◆ Thinner T88